

C l a i m s

1. Adhesive closure part (1, 101, 201, 301) with a plurality of adhesive closure elements (2) such as for example hooks, mushrooms or loops, the adhesive closure part (1, 101, 201, 301) having a flat carrier (3, 103, 203, 303) and the adhesive closure elements (2) projecting from at least one surface (4) of the carrier (3, 103, 203, 303), **characterized in that** the adhesive closure part (1, 101, 201, 301) has a circuit (5, 305) which has at least one electrical and/or electronic component (6, 106; 7, 107, 207, 307).
2. Adhesive closure part (1, 101, 201, 301) as claimed in claim 1, wherein the electrical and/or electronic component (6, 106; 7, 107, 207, 307) is located on and/or in the flat carrier (3, 103, 203, 303).
3. Adhesive closure part (1, 101, 201, 301) as claimed in claim 1 or 2, wherein the electrical and/or electronic component (6, 106; 7, 107, 207, 307) is integrated into the flat carrier (3, 103, 203, 303).
4. Adhesive closure part (1, 101, 201, 301) as claimed in one of claims 1 to 3, wherein the electrical and/or electronic component (6, 106; 7, 107, 207, 307) is applied in thick or thin film technology to the flat carrier (3, 103, 203, 303).
5. Adhesive closure part (201) as claimed in one of claims 1 to 4, wherein the electrical and/or electronic component (6, 106; 7, 107, 207, 307) is applied to another carrier (212) which is laminated onto the flat carrier (3, 103, 203, 303) of the adhesive closure part (1, 101, 201, 301).
6. Adhesive closure part (1, 101, 201, 301) as claimed in one of claims 1 to 5, wherein the circuit (5, 305) has electrical conductor strips (6, 106).

7. Adhesive closure part (1, 101, 201, 301) as claimed in one of claims 1 to 6, wherein the circuit (5, 305) has electrical and/or electronic sensors (306a, 306b).
8. Adhesive closure part (1, 101, 201, 301) as claimed in one of claims 1 to 7, wherein the circuit (5, 305) has an integrated semiconductor component (7, 107, 207, 307).
9. Adhesive closure part (1, 101, 201, 301) as claimed in claim 8, wherein the integrated semiconductor component (7, 107, 207, 307) has an electronic data memory (17).
10. Adhesive closure part (1, 101, 201, 301) as claimed in claim 9, wherein the data stored in the data memory (17) can be read out without contact.
11. Adhesive closure part (1, 101, 201, 301) as claimed in claim 9 or 10, wherein data can be stored in the data memory (17) without contact.
12. Adhesive closure part (1, 101, 201, 301) as claimed in one of claims 1 to 11, wherein the electrical energy for operating the circuit (5, 305) can be coupled into the circuit (5, 305) which has at least one receiving coil for this purpose without contact by an electromagnetic field.
13. Adhesive closure part (1, 101, 201, 301) as claimed in one of claims 1 to 12, wherein the circuit (5, 305) has an energy storage device (318), especially an electrochemical energy storage device (318) in thin or thick film technology.
14. Adhesive closure part (1, 101, 201, 301) as claimed in one of claims 1 to 13, wherein the carrier (3, 103, 203, 303) and/or the adhesive closure elements (2) are produced from a duroplastic, thermoplastic, polymer plastic or an acrylate plastic.